This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:** 

1. (Currently Amended) A method for forming a pattern of a liquid crystal display

(LCD) device, comprising:

providing a cliché having at least a first groove structure having a first width and a

second groove structure having a second width divided into multiples of the first width and an

interval therebetween;

filling a resist material into the first and second groove structures of the cliché, wherein

the interval is determined by viscosity and surface energy of the resist material; and

applying the resist material filled into the first and second groove structures of the cliché

onto an etching object layer of a substrate of the liquid crystal display device.

2. (Currently Amended) The method of claim 1, wherein providing a cliché comprises:

including providing a cliché substrate, forming a buffer layer on the cliché substrate, and forming

the first and second groove structures by patterning the buffer layer.

3. (Original) The method of claim 2, wherein the buffer layer includes a metal layer.

4. (Original) The method of claim 2, wherein the buffer layer includes an organic layer.

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5. (Original) The method of claim 1, wherein applying the resist material onto an etching object layer comprises:

contacting and rotating a printing roll onto the cliché to transfer the resist material filled in the first and second groove structures to a surface of the printing roll; and

contacting the resist material formed on the surface of the printing roll to transfer the resist material from the printing roll onto the etching object layer by rotating the printing roll.

6. (Previously Presented) The method of claim 1, wherein applying the resist material onto an etching object layer comprises:

contacting the etching object layer formed on the substrate of the liquid crystal display device with the cliché;

applying heat or pressure to the substrate of the liquid crystal display device; and detaching the substrate of the liquid crystal display device from the cliché to transfer the resist material filled in the first and second groove structures onto the etching object layer.

- 7. (Original) The method of claim 1, wherein the etching object layer includes a metal layer.
- 8. (Original) The method of claim 1, wherein the etching object layer includes one of SiNx and SiOx.
- 9. (Original) The method of claim 1, wherein the etching object layer includes an organic layer.

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10. (Previously Presented) The method of claim 1, wherein filling a resist material into

the first and second groove structures of the cliché comprises:

depositing the resist material along an entire surface of the cliché; and

contacting a doctor blade onto the surface of the cliché, flattening the resist material into

the first and second groove structures and removing the resist material that remains on the

surface of the cliché.

11. (Currently Amended) A method for forming a pattern of an LCD device,

comprising:

forming a buffer layer on a substrate by depositing one of an organic material and a metal

material;

providing a cliché having at least first and second groove structures by patterning the

buffer layer, the first groove structure having a first width and the second groove structure

having a second width divided into multiples of the first width and an interval therebetween,

wherein the interval is determined by viscosity and surface energy of the resist material;

depositing a resist material onto a surface of the cliché;

flattening the resist material into the first and second groove structures and removing the

resist material from the surface of the cliché;

transferring the resist material filled in the first and second groove structure of the cliché

onto a printing roll; and

applying the resist material formed onto the printing roll onto an etching object layer to

form a resist pattern having a uniform thickness.

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12. (Currently Amended) A method for forming a pattern of an LCD device,

comprising:

forming a buffer layer on a substrate of a cliché by depositing one of an organic material

and a metal material on the cliché substrate;

providing on the cliché substrate at least a first groove structure having a first width and a

second groove structure having a second width divided into multiples of the first width and an

interval therebetween, wherein the interval is determined by viscosity and surface energy of the

resist material;

depositing a resist material on a surface of the cliché;

flattening the resist material into the first and second groove structures and removing the

resist material that remains on the surface of the cliché;

forming an etching object layer on a substrate of the LCD device, attaching the substrate

of the LCD device, including the etching object layer onto the cliché and applying at least one of

heat and pressure; and

detaching the substrate of the LCD device, including the etching object layer, from the

cliché to transfer the resist material filled in the first and second groove structures of the cliché

onto the etching object layer and to form a resist pattern.

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